

Docket No.: 1268-260

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
Einar NYGARD : Confirmation No. -----
U.S. Patent Application No. ----- : Group Art Unit: -----
Filed: *herewith* : Examiner: -----

For: PIXEL DETECTOR AND METHOD OF MANUFACTURE AND ASSEMBLY
THEREOF

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

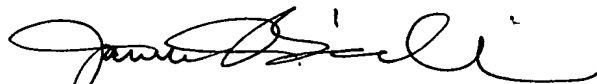
Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

Respectfully submitted,

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 1268-260		U.S. APPLICATION NO. Not yet assigned	
				APPLICANT Einar NYGARD			
				FILING DATE herewith		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	5 254 868	10/19/1993	SAITO				
	5 998 292	12/07/1999	BLACK et al				
	4 547 792	10/15/1985	SCLAR				
	4 857 746	08/15/1989	KUHLMANN et al				
	5 132 539	07/21/1992	KWASNICK et al				
	6 416 218 B1	07/09/2002	CHEUNG				
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation Yes No	
	03/083944 A1	10/09/2003	WO				
	1 045 450 A3	05/29/2002	EP				
	0 537 514 A2	04/21/1993	EP				
	1 253 442 A1	10/30/2002	EP				
	61 128 564 A2	06/16/1986	JP			abstract	
	02/067014 A1	08/29/2002	wo				
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	Tewksbury et al; "Cointegration of Optoelectronics and Submicron CMOS"; Wafer Scale Information, 1993. Proceedings., Fifth Annual IEEE International Conference on San Francisco, CA USA; January 20, 1993; pages 358-367; XP010067696						
	Flack et al; "Lithographic Manufacturing Techniques for Wafer Scale Integration"; Wafer Scale Integration, 1992. Proceedings., Fourth International Conference on San Francisco, CA USA, January 22, 1992; pages 4-13, XP010026528						
	Banthien et al; "A Vertically Integrated High Resolution Active Pixel Image Sensor for Deep Submicron CMOS Processes; presented to 1999 IEEE Workshop on CCDs and Advance Image Sensors, Nagano Japan, June 10-12, 1999						
EXAMINER				DATE CONSIDERED			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.